

## Reverse Blocking Triode Thyristor

### Features and Benefits

- Exceptional reliability
- Small fully-molded SIP package with heatsink mounting for high thermal dissipation and long life
- Operating junction temperature to 150°C
- $V_{DRM}$  of 700 or 800 V
- 15.7  $A_{RMS}$  on-state current
- 7 mA typical gate trigger current
- Uniform switching
- UL Recognized Component (File No.: E118037) (suffix I)



Package: 3-pin SIP (TO-220F)



Not to scale

### Description

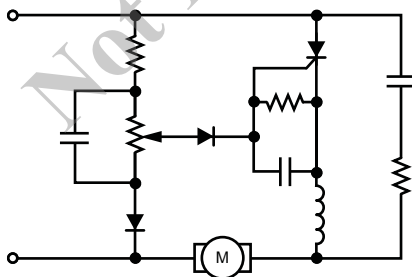
This SanKen reverse blocking triode thyristor is designed for AC power control, providing reliable, uniform switching for half-cycle AC applications.

In comparison with other products on the market, the TFA10x series provides increased isolation voltage (1800  $V_{AC_{RMS}}$ ), guaranteed for up to 1 minute. In addition, commutation  $dv/dt$  is improved.

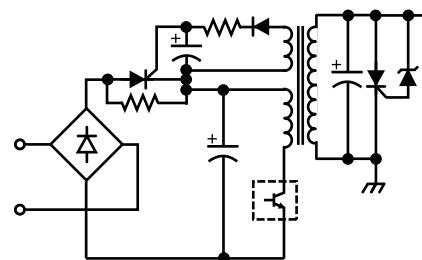
### Applications

- Motor control for small tools
- Temperature control, light dimmers, electric blankets
- General use switching mode power supplies (SMPS)

### Typical Applications



Single-phase motor control (for example, electric tool)



In-rush current control (for example, SMPS)

# TFA10x Series

## Reverse Blocking Triode Thyristor

### Selection Guide

| Part Number | V <sub>DRM</sub> (V) | UL-Recognized Component | Package                                    | Packing            |
|-------------|----------------------|-------------------------|--|--------------------|
| TFA107(I)   | 700                  | Yes                     | 3-pin fully molded SIP with heatsink mount | 50 pieces per tube |
| TFA107S     | 700                  | –                       |  |                    |
| TFA108(I)   | 800                  | Yes                     |  |                    |
| TFA108S     | 800                  | –                       |  |                    |

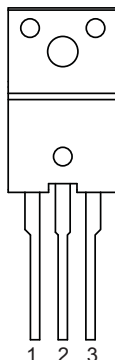
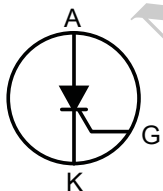
### Absolute Maximum Ratings

| Characteristic                           | Symbol              | Notes  | Rating  | Units             |   |
|--|---------------------|--|---|-------------------|---|
| Peak Repetitive Off-State Voltage        | V <sub>DRM</sub>    | TFA107x  | T <sub>J</sub> = –40°C to 150°C, R <sub>GREF</sub> = 1 kΩ | 700               | V |
|  |                     | TFA108x  |   | 800               | V |
| Isolation Voltage                        | V <sub>ISO</sub>    | AC RMS applied for 1 minute between lead and case  | 1800  | V                 |   |
| Average On-State Current                 | I <sub>T(AV)</sub>  | 50 Hz half cycle sine wave, Conduction angle (α) = 180°, continuous operation, T <sub>C</sub> = 86°C   | 10.0  | A                 |   |
| RMS On-State Current                     | I <sub>T(RMS)</sub> |  | 15.7  | A                 |   |
| Surge On-State Current                   | I <sub>TSM</sub>    | f = 60 Hz  | Half cycle sine wave, single, non-repetitive              | 176               | A |
|  |                     | f = 50 Hz  |   | 160               | A |
| I <sup>2</sup> t Value for Fusing        | I <sup>2</sup> t    | Value for 50 Hz half cycle sine wave, 1 cycle, I <sub>TSM</sub> = 160 A  | 128   | A <sup>2</sup> ·s |   |
| Critical Rising Rate of On-State Current | di/dt               | I <sub>T</sub> = I <sub>T(RMS)</sub> × π, V <sub>D</sub> = V <sub>DRM</sub> × 0.5, f ≤ 60 Hz, t <sub>gw</sub> ≥ 10 μs, t <sub>gr</sub> ≤ 250 ns, I <sub>gp</sub> ≥ 30 mA (refer to Gate Trigger Circuit diagram) | 50  | A/μs              |   |
| Peak Forward Gate Current                | I <sub>FGM</sub>    | f ≥ 50 Hz, duty cycle ≤ 10%  | 2.0   | A                 |   |
| Peak Forward Gate Voltage                | V <sub>FGM</sub>    | f ≥ 50 Hz, duty cycle ≤ 10%  | 10  | V                 |   |
| Peak Reverse Gate Current                | V <sub>RGM</sub>    | f ≥ 50 Hz  | 5.0   | V                 |   |
| Peak Gate Power Dissipation              | P <sub>GM</sub>     | f ≥ 50 Hz, duty cycle ≤ 10%  | 5.0   | W                 |   |
| Average Gate Power Dissipation           | P <sub>GM(AV)</sub> | T <sub>J</sub> < T <sub>J(max)</sub>   | 0.5   | W                 |   |
| Junction Temperature                     | T <sub>J</sub>      |  | –40 to 150  | °C                |   |
| Storage Temperature                      | T <sub>stg</sub>    |  | –40 to 150  | °C                |   |

### Thermal Characteristics May require derating at maximum conditions

| Characteristic                                | Symbol           | Test Conditions | Value | Units |
|---|------------------|-----------------|-------|-------|
| Package Thermal Resistance (Junction to Case) | R <sub>θJC</sub> | For AC          | 3.4   | °C/W  |

### Pin-out Diagram



### Terminal List Table

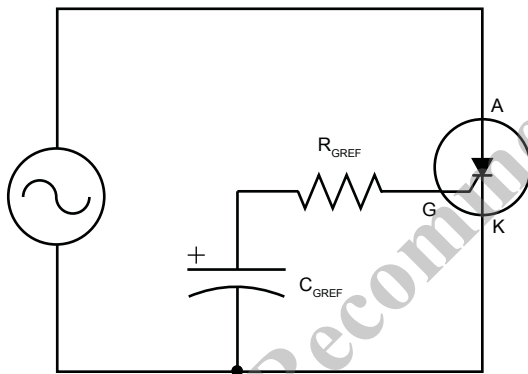
| Number | Name | Function         |
|--------|------|------------------|
| 1      | K    | Cathode terminal |
| 2      | A    | Anode terminal   |
| 3      | G    | Gate control     |

All performance characteristics given are typical values for circuit or system baseline design only and are at the nominal operating voltage and an ambient temperature, T<sub>A</sub>, of 25°C, unless otherwise stated.

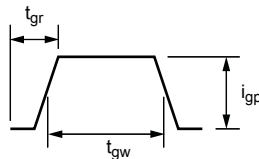
### ELECTRICAL CHARACTERISTICS

| Characteristics                           | Symbol    | Test Conditions  | Min. | Typ. | Max. | Unit             |
|---|-----------|--|------|------|------|------------------|
| Off-State Leakage Current                 | $I_{DRM}$ | $V_D = V_{DRM}$ , $T_J = 150^\circ\text{C}$ , $R_{GREF} = 1\text{ k}\Omega$  | -    | -    | 2.0  | mA               |
| Reverse Leakage Current                   | $I_{RRM}$ | $V_D = V_{DRM}$ , $T_J = 150^\circ\text{C}$ , $R_{GREF} = 1\text{ k}\Omega$  | -    | -    | 2.0  | mA               |
| On-State Voltage                          | $V_{TM}$  | $I_{TM} = 20\text{ A}$ , $T_C = 25^\circ\text{C}$  | -    | -    | 1.35 | V                |
| Gate Trigger Voltage                      | $V_{GT}$  | $V_D = 6\text{ V}$ , $R_L = 10\ \Omega$ , $T_C = 25^\circ\text{C}$   | -    | -    | 1.0  | V                |
| Gate Trigger Current                      | $I_{GT}$  | $V_D = 6\text{ V}$ , $R_L = 10\ \Omega$ , $T_C = 25^\circ\text{C}$   | -    | 7    | 15   | mA               |
| Gate Non-trigger Voltage                  | $V_{GD}$  | $V_D = V_{DRM} \times 0.5$ , $R_{GREF} = 1\text{ k}\Omega$ , $T_J = 125^\circ\text{C}$                                   | 0.2  | -    | -    | V                |
| Holding Current                           | $I_H$     | $R_{GREF} = 1\text{ k}\Omega$ , $T_J = 25^\circ\text{C}$   | -    | 20   | -    | mA               |
| Critical Rising Rate of Off-State Voltage | dv/dt     | $V_D = V_{DRM} \times 0.5$ , $T_J = 125^\circ\text{C}$ , $R_{GREF} = 1\text{ k}\Omega$ , $C_{GREF} = 0.033\ \mu\text{F}$ | -    | 300  | -    | V/ $\mu\text{s}$ |

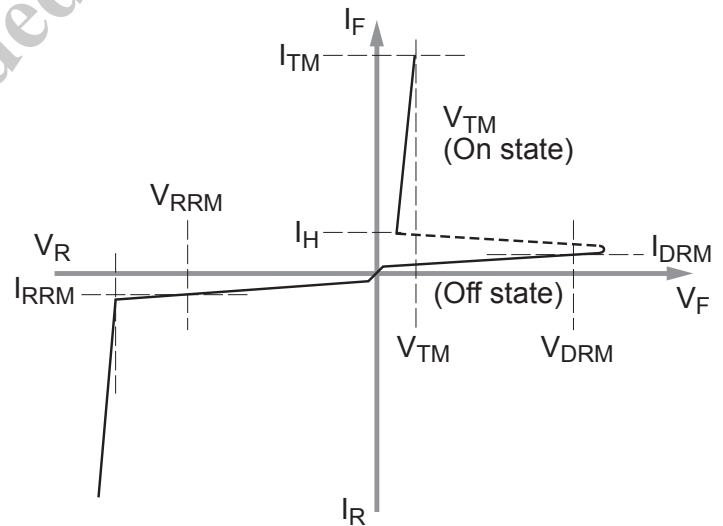
Test Circuit 1



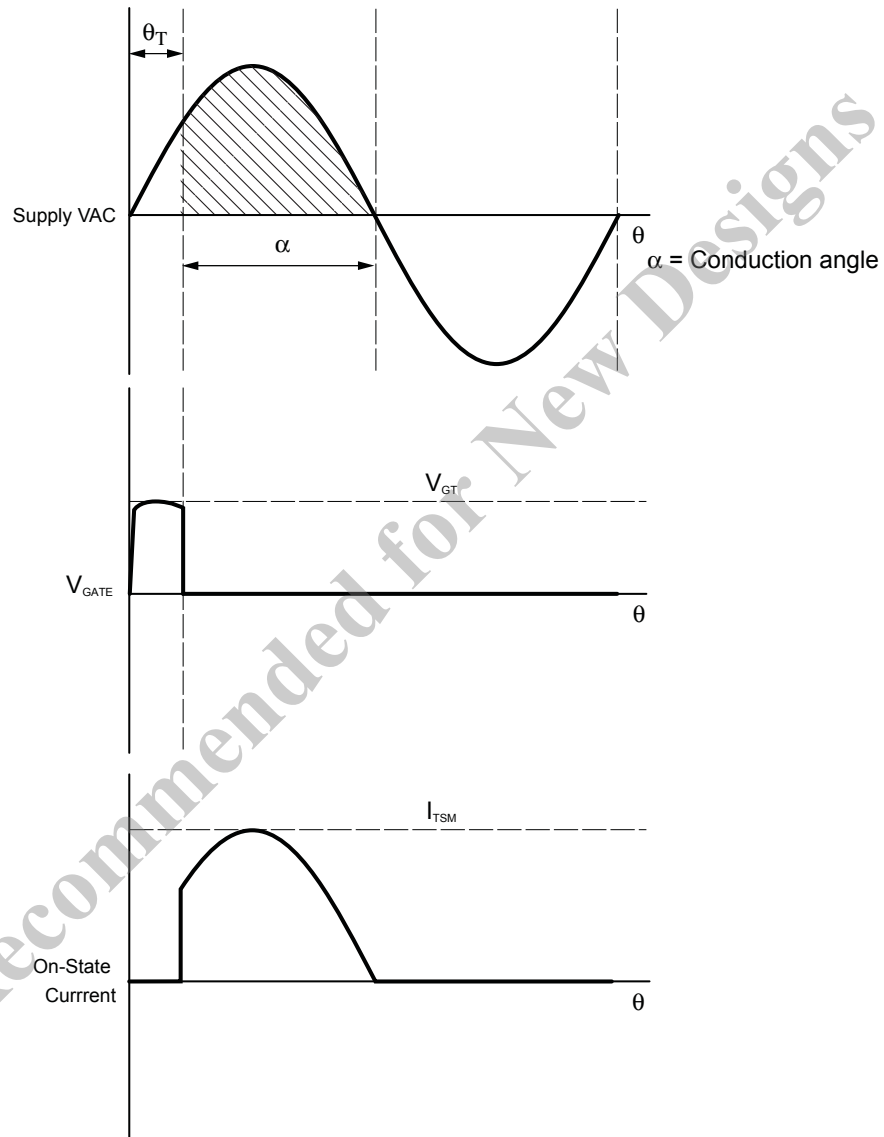
Gate Trigger Current



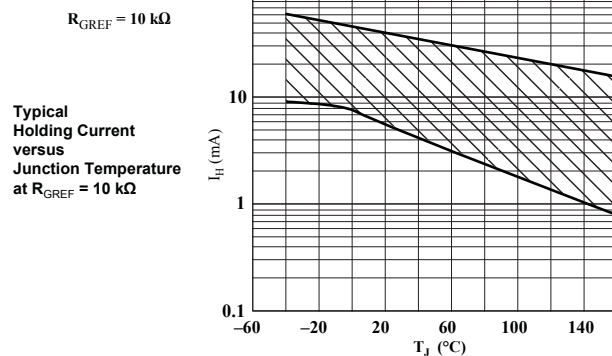
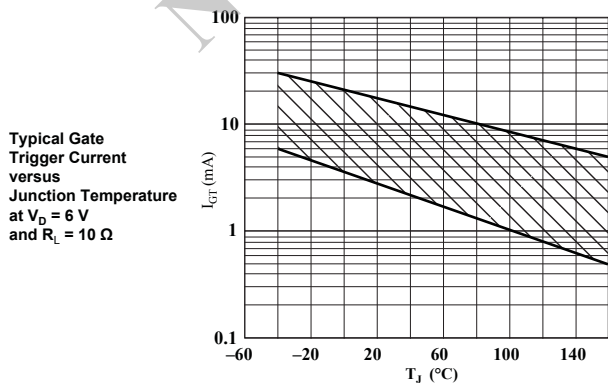
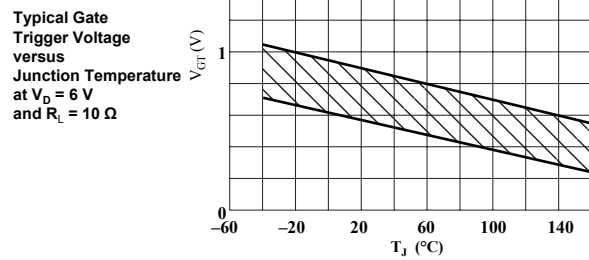
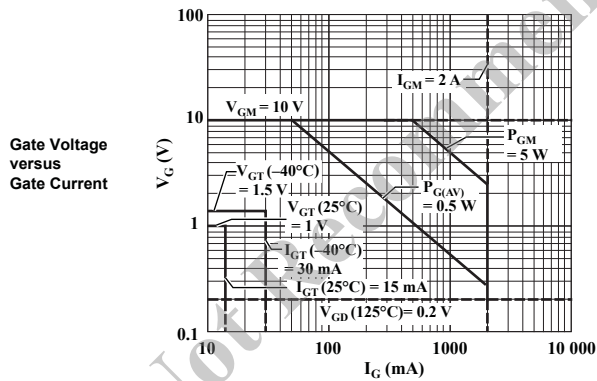
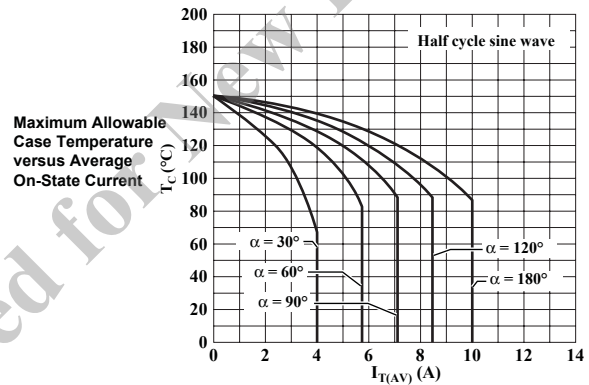
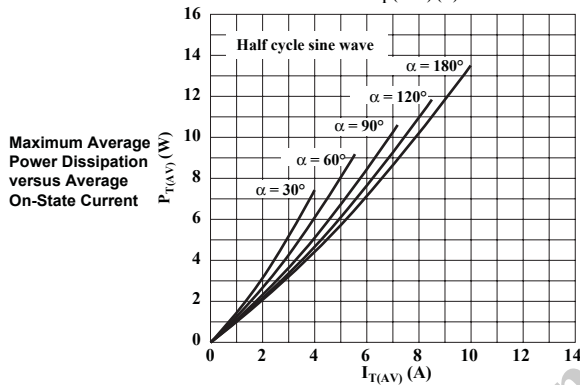
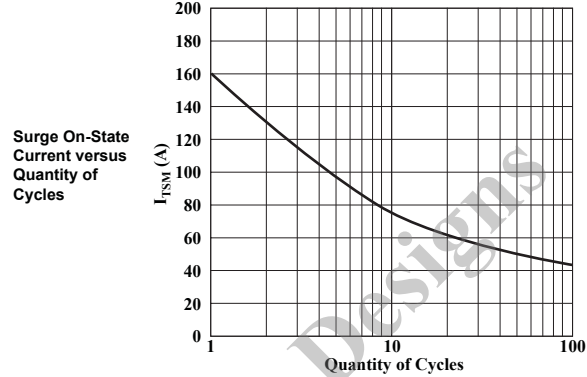
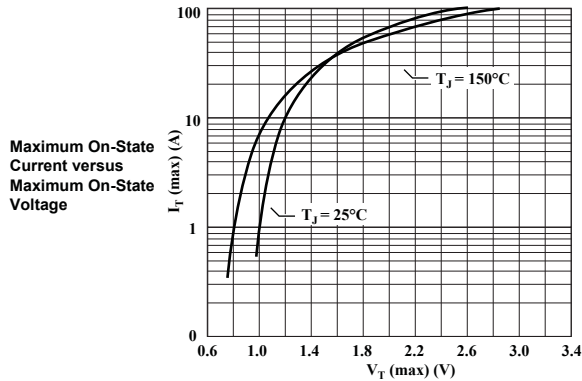
Voltage-Current Characteristic

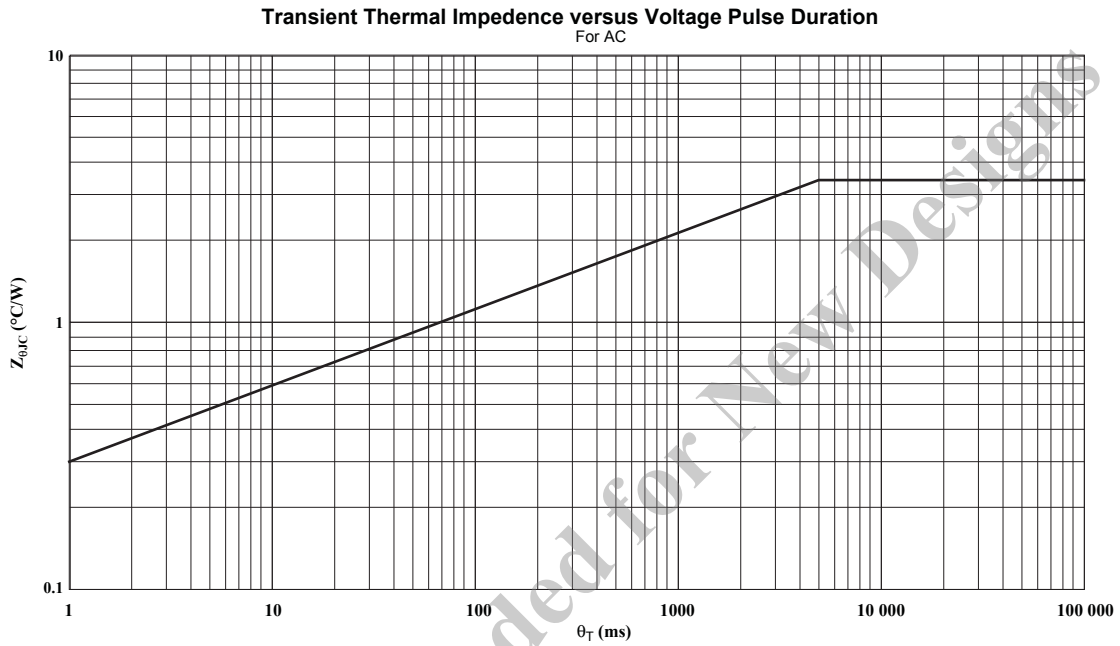


Commutation Timing Diagrams



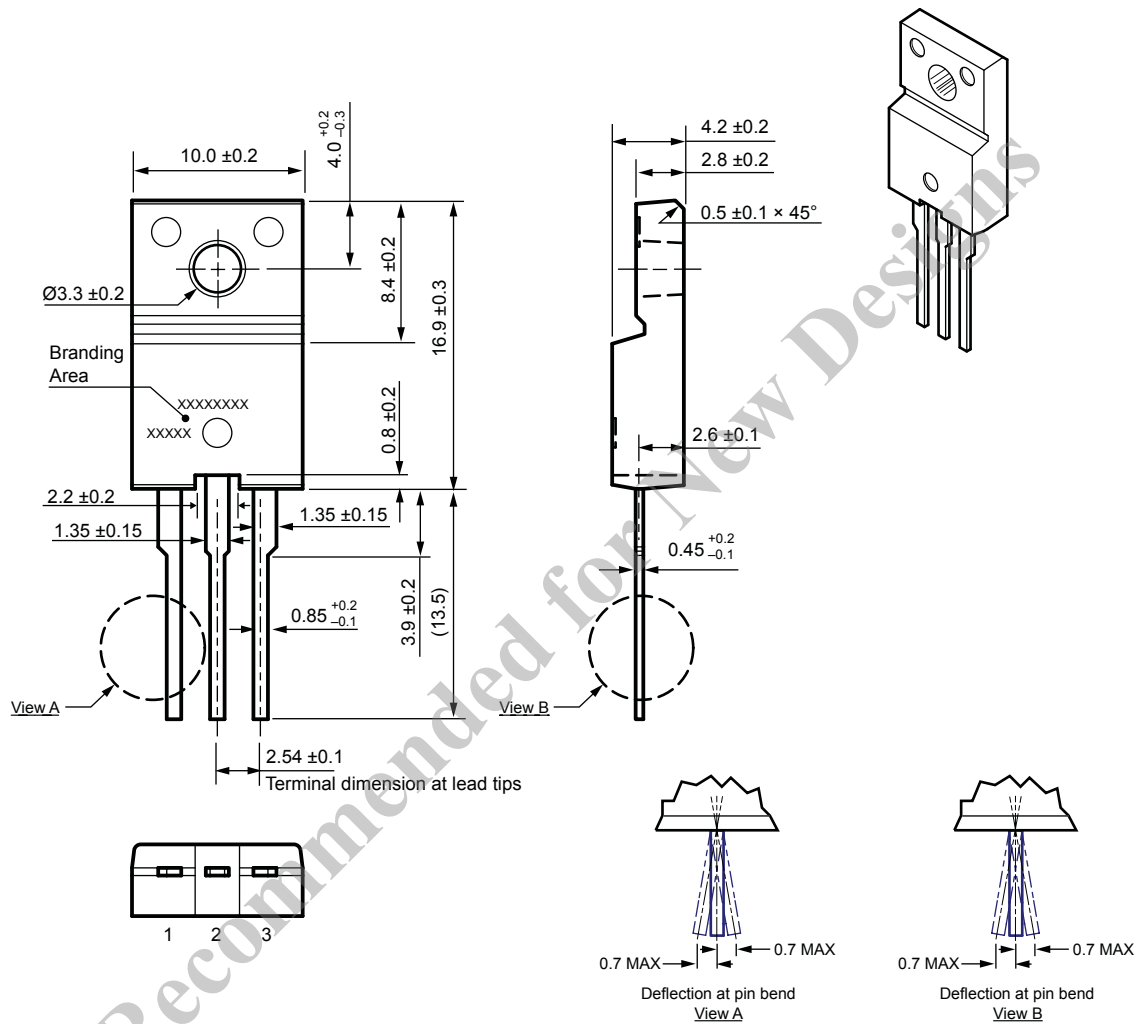
## Performance Characteristics at $T_A = 25^\circ\text{C}$





Not Recommended for New Designs

## TO-220F Package Outline Drawing



Gate burr: 0.3 mm (max.), mold flash may appear at opposite side  
 Terminal core material: Cu  
 Terminal treatment: Ni plating and Pb-free solder dip  
 Leadform: 600  
 Package: TO-220F (FM20)

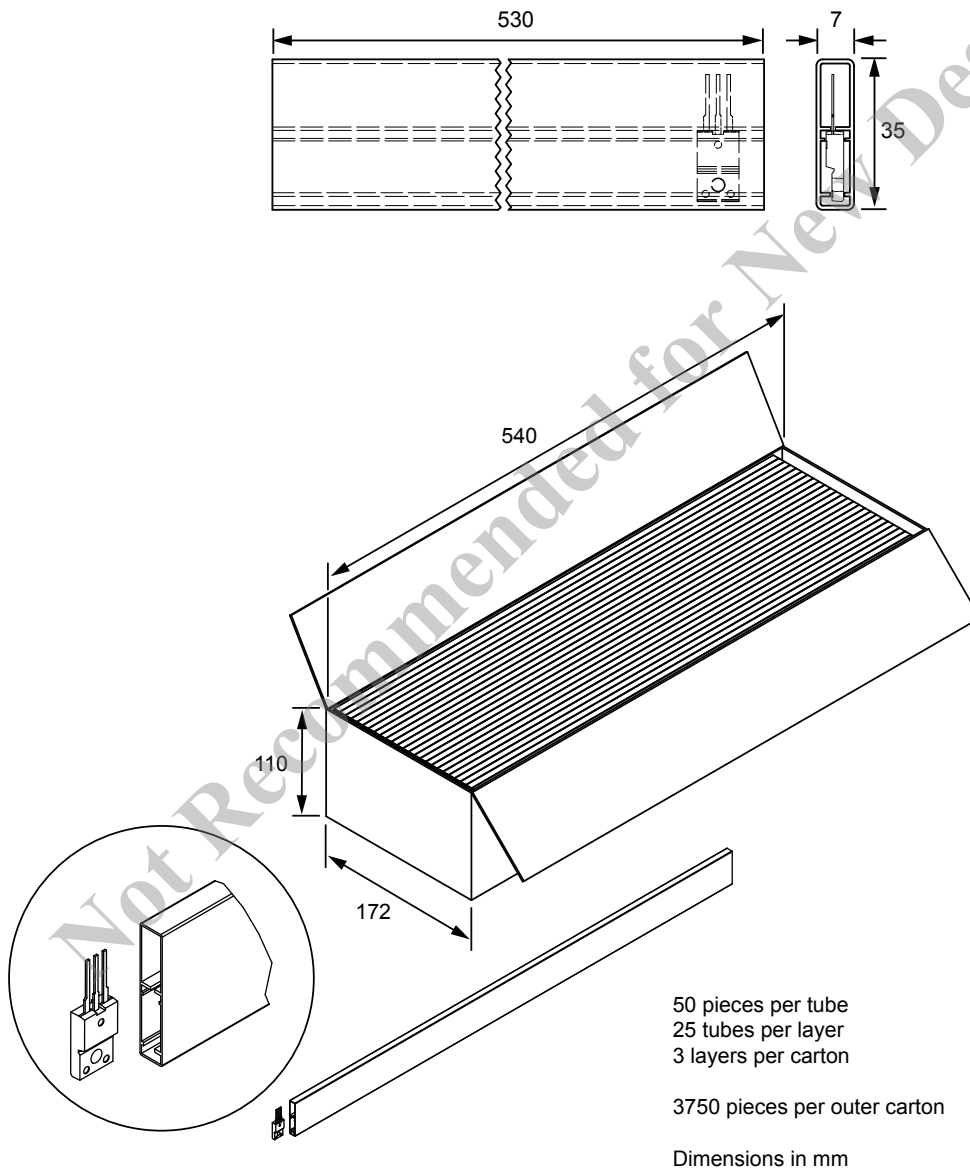
Branding codes (exact appearance at manufacturer discretion):  
 1st line, type: FA10xx  
 2nd line, lot: YM  
 Where: Y is the last digit of the year of manufacture  
 M is the month (1 to 9, O, N, D)

Dimensions in millimeters



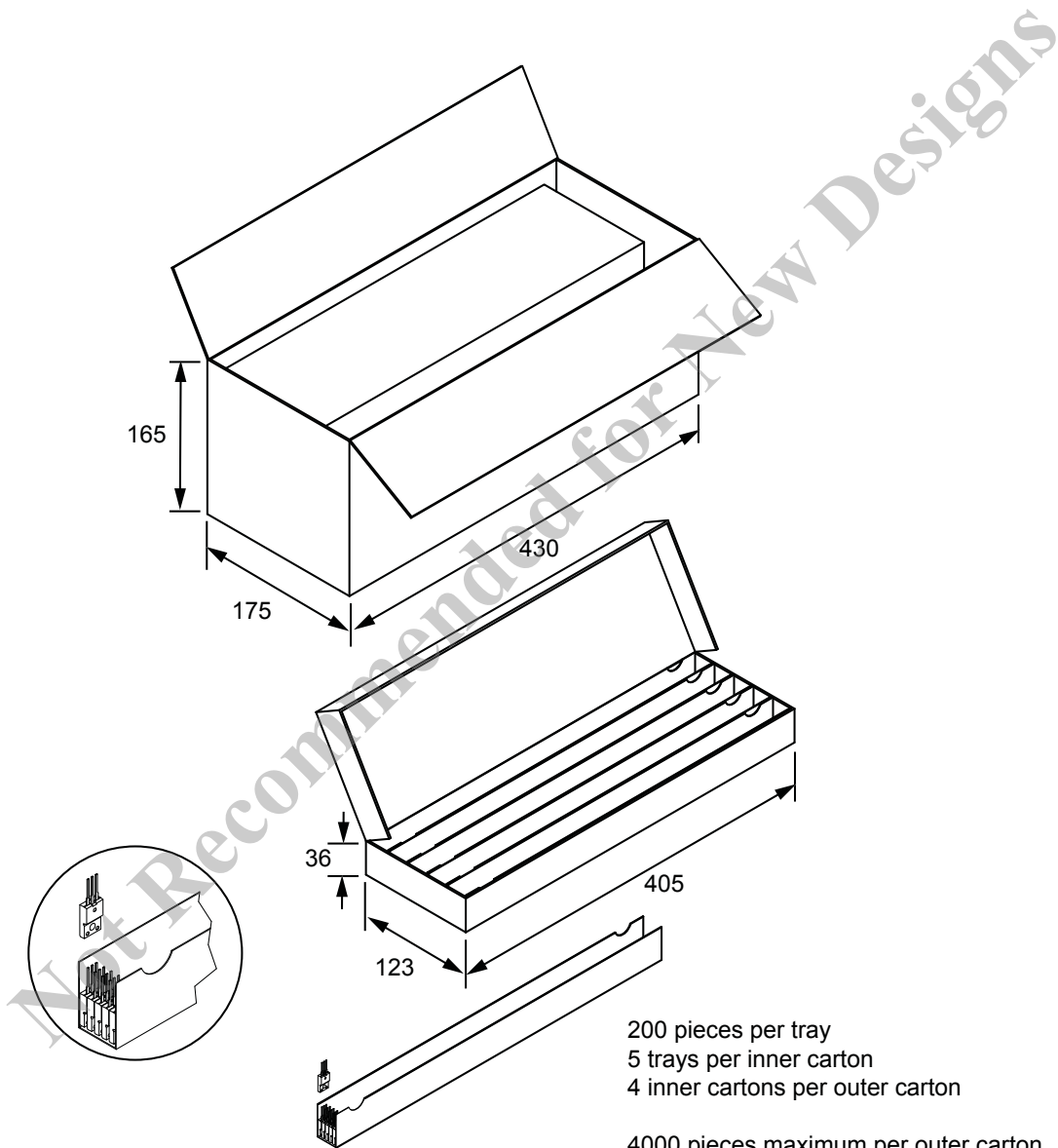
Leadframe plating Pb-free. Device meets RoHS requirements.

**Packing Specification**  
Tube Packing

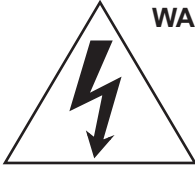




Bulk Packing



200 pieces per tray  
5 trays per inner carton  
4 inner cartons per outer carton  
4000 pieces maximum per outer carton  
Dimensions in millimeters



**WARNING** — These devices are designed to be operated at lethal voltages and energy levels. Circuit designs that embody these components must conform with applicable safety requirements. Precautions must be taken to prevent accidental contact with power-line potentials. Do not connect grounded test equipment.

The use of an isolation transformer is recommended during circuit development and breadboarding.

Because reliability can be affected adversely by improper storage environments and handling methods, please observe the following cautions.

#### Cautions for Storage

- Ensure that storage conditions comply with the standard temperature (5°C to 35°C) and the standard relative humidity (around 40 to 75%); avoid storage locations that experience extreme changes in temperature or humidity.
- Avoid locations where dust or harmful gases are present and avoid direct sunlight.
- Reinspect for rust on leads and solderability of products that have been stored for a long time.

#### Cautions for Testing and Handling

When tests are carried out during inspection testing and other standard test periods, protect the products from power surges from the testing device, shorts between adjacent products, and shorts to the heatsink.

#### Remarks About Using Silicone Grease with a Heatsink

- When silicone grease is used in mounting this product on a heatsink, it shall be applied evenly and thinly. If more silicone grease than required is applied, it may produce stress.
- Coat the back surface of the product and both surfaces of the insulating plate to improve heat transfer between the product and the heatsink.
- Volatile-type silicone greases may permeate the product and produce cracks after long periods of time, resulting in reduced heat radiation effect, and possibly shortening the lifetime of the product.
- Our recommended silicone greases for heat radiation purposes, which will not cause any adverse effect on the product life, are indicated below:

| Type   | Suppliers                            |
|--------|--------------------------------------|
| G746   | Shin-Etsu Chemical Co., Ltd.         |
| YG6260 | Momentive Performance Materials      |
| SC102  | Dow Corning Toray Silicone Co., Ltd. |

#### Heatsink Mounting Method

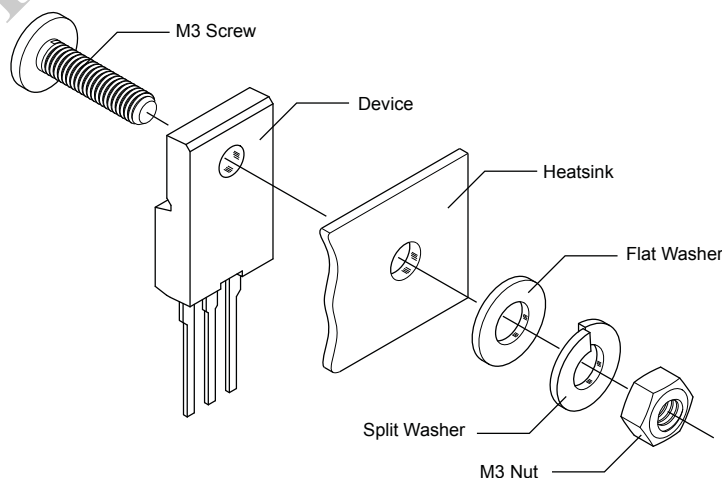
- **Torque When Tightening Mounting Screws.** Thermal resistance increases when tightening torque is low, and radiation effects are decreased. When the torque is too high, the screw can strip, the heatsink can be deformed, and distortion can arise in the product frame. To avoid these problems, observe the recommended tightening torques for this product package type 0.490 to 0.686 N·m (5 to 7 kgf·cm).
- For effective heat transfer, the contact area between the product and the heatsink should be free from burrs and metal fragments, and the heatsink should be flat and large enough to contact over the entire side of the product, including mounting flange and exposed thermal pad.
- The mounting hole in customer-supplied heatsink must be less than  $\varnothing 4$  mm; this includes the diameter of any dimple around punched holes. This is to prevent possible deflection and cracking of the product case when fastened to the heatsink.

#### Soldering

- When soldering the products, please be sure to minimize the working time, within the following limits:  
 $260 \pm 5^\circ\text{C}$  10 s  
 $350 \pm 5^\circ\text{C}$  3 s
- Soldering iron should be at a distance of at least 1.5 mm from the body of the products

#### Electrostatic Discharge

- When handling the products, operator must be grounded. Grounded wrist straps worn should have at least 1 M $\Omega$  of resistance to ground to prevent shock hazard.
- Workbenches where the products are handled should be grounded and be provided with conductive table and floor mats.
- When using measuring equipment such as a curve tracer, the equipment should be grounded.
- When soldering the products, the head of soldering irons or the solder bath must be grounded in order to prevent leak voltages generated by them from being applied to the products.
- The products should always be stored and transported in our shipping containers or conductive containers, or be wrapped in aluminum foil.



The products described herein are manufactured in Japan by SanKen Electric Co., Ltd. for sale by Allegro MicroSystems, Inc.

SanKen and Allegro reserve the right to make, from time to time, such departures from the detail specifications as may be required to permit improvements in the performance, reliability, or manufacturability of its products. Therefore, the user is cautioned to verify that the information in this publication is current before placing any order.

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Anti radioactive ray design is not considered for the products listed herein.

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